SURFACE MOUNT RECTIFIER

REVERSE VOLTAGE: 50 - 1000 V
CURRENT: 1.0 A

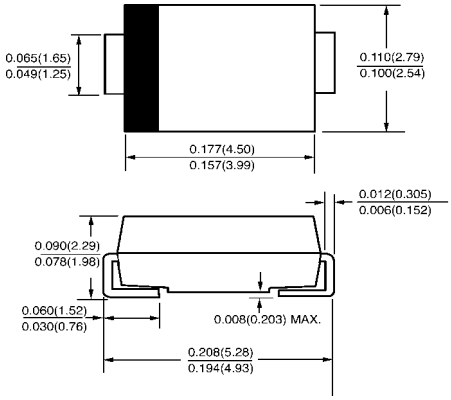
FEATURES

- ◇Plastic package has underwriters laboratory flammability classifications
- ◇For surface mounted applications
- ◇Low profile package
- ◇Built-in strain relief,ideal for automated placement
- ◇Glass passivated chip junction
- ◇High temperature soldering: 250°C/10 seconds at terminals

MECHANICAL DATA

- ◇Case:JEDEC DO-214AC,molded plastic over passivated chip
- ◇Terminals:Solder Plated, solderable per MIL-STD-750, Method 2026
- ◇Polarity: Color band denotes cathode end
- ◇Weight: 0.002 ounces, 0.064 gram

DO - 214AC(SMA)



inch(mm)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified

		S1A	S1B	S1D	S1G	S1J	S1K	S1M	UNITS
Device marking code		SA	SB	SD	SG	SJ	SK	SM	
Maximum recurrent peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum average forword rectified current @T_L=110℃	$I_{F(AV)}$	1.0							A
Peak forward surge current @ T_L = 110°C 8.3ms single half-sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	40.0					30.0		A
Maximum instantaneous forward voltage at 1.0A	V_F	1.1							V
Maximum DC reverse current @T_A=25°C at rated DC blockjing voltage @T_A=125°C	I_R	5.0 50.0							μA
Typical junction capacitance(NOTE 1)	C_J	15							pF
Typical thermal resitance (NOTE 2)	$R_{\theta JA}$	50							°C/W
Operating junction and storage temperature range	$T_J T_{STG}$	-55--------+175							°C

NOTE: 1.Measured at 1.0MHz and applied reverse voltage of 4.0volts

2.Thermal resistance form junction to ambient and junction to lead P.C.B mounted on 0.27"X0.27"(7.0X7.0mm2) copper pad areas.

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FIG.1 – FORWARD DERATING CURVE

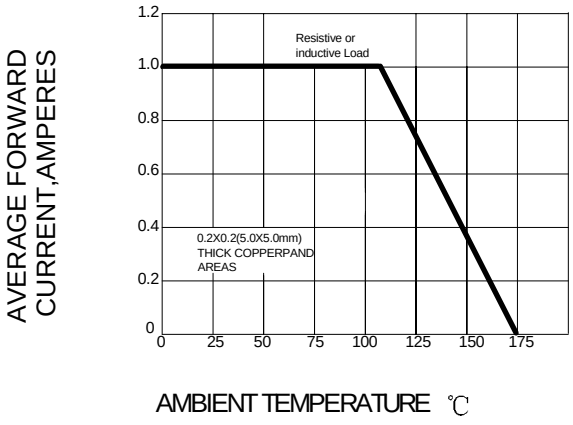

FIG.2 PEAK FORWARD SURGE CURRENT

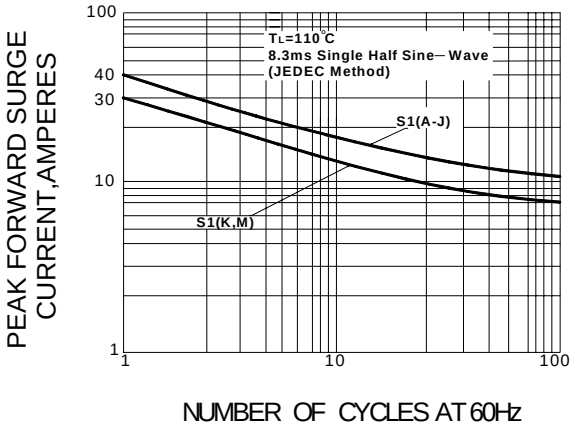

FIG.3 – TYPICAL FORWARD CHARACTERISTICS

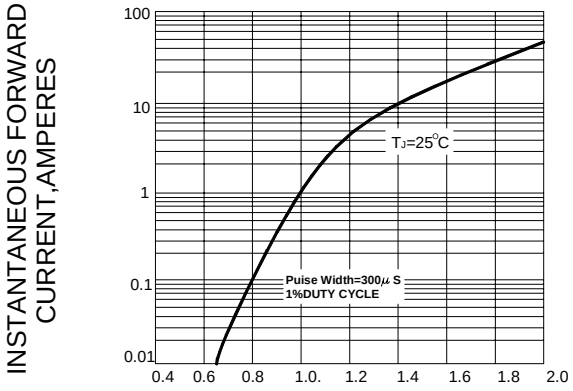

FIG.4 – TYPICAL REVERSE CHARACTERISTICS

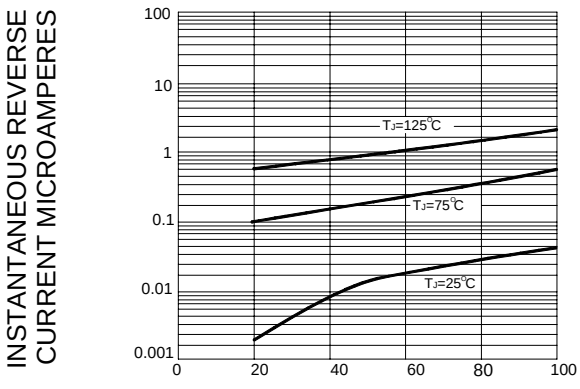

FIG.5-TYPICAL JUNCTION CAPACITANCE

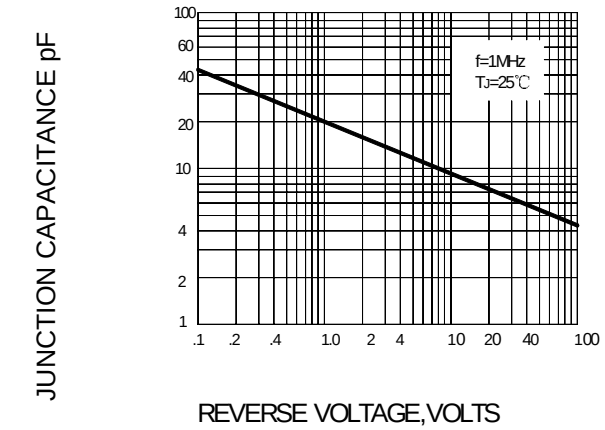

FIG.6-TRANSIENT THERMAL IMPEDANCE